

20V N-Channel Enhancement Mode Power MOSFET

Description

EMR13N02TS uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

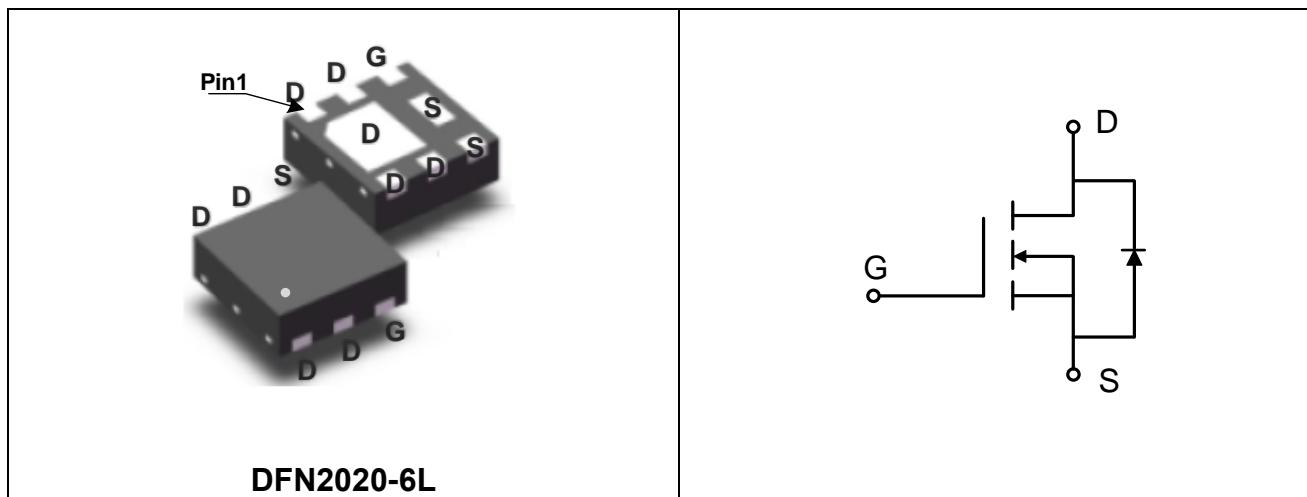
Features

- $V_{DS} = 20V$, $I_D = 13A$
 $R_{DS(on)} < 10m\Omega$ @ $V_{GS} = 4.5V$
 $R_{DS(on)} < 13.5m\Omega$ @ $V_{GS} = 2.5V$
- Green Device Available
- RoHS Compliant & Halogen-Free
- Super Low Gate Charge

Applications

- Load Switches
- DC/DC Converter

Schematic & PIN Configuration



EMR13N02TS

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current	I_D	13	A
		8	
Pulsed Drain Current ⁽¹⁾	I_{DM}	52	A
Single Pulse Avalanche Energy ⁽²⁾	EAS	42.25	mJ
Total Power Dissipation	P_D	2.8	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction to Ambient ⁽³⁾	$R_{\theta JA}$	44.6	$^\circ\text{C/W}$

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Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	20	-	-	V
Gate-body Leakage Current	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 12\text{V}$	-	-	± 100	nA
Zero Gate Voltage Drain Current $T_J=25^\circ\text{C}$	I_{DSS}	$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}$	-	-	1	μA
$T_J=100^\circ\text{C}$			-	-	100	
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	0.5	0.75	1	V
Drain-Source on-state Resistance ⁽⁴⁾	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 4.5\text{V}, I_D = 10\text{A}$	-	7.8	10	$\text{m}\Omega$
		$V_{\text{GS}} = 2.5\text{V}, I_D = 5\text{A}$	-	10	13.5	
Forward Transconductance ⁽⁴⁾	g_{fs}	$V_{\text{DS}} = 4.5\text{V}, I_D = 10\text{A}$	-	44	-	S
Dynamic Characteristics ⁽⁵⁾						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 10\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$	-	1259	-	pF
Output Capacitance	C_{oss}		-	160	-	
Reverse Transfer Capacitance	C_{rss}		-	155	-	
Switching Characteristics ⁽⁵⁾						
Total Gate Charge	Q_g	$V_{\text{GS}} = 4.5\text{V}, V_{\text{DS}} = 10\text{V}, I_D = 10\text{A}$	-	13.5	-	nC
Gate-Source Charge	Q_{gs}		-	2.9	-	
Gate-Drain Charge	Q_{gd}		-	2.9	-	
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{GS}} = 4.5\text{V}, V_{\text{DD}} = 10\text{V}, R_G = 3\Omega, I_D = 10\text{A}$	-	5.5	-	ns
Rise Time	t_r		-	8.9	-	
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	9.8	-	
Fall Time	t_f		-	22.9	-	
Body Diode Reverse Recovery Time	t_{rr}	$I_F = 10\text{A}, dI/dt = 100\text{A}/\mu\text{s}$	-	22	-	ns
Body Diode Reverse Recovery Charge	Q_{rr}		-	3.5	-	nC
Drain-Source Body Diode Characteristics						
Body Forward Voltage ⁽⁴⁾	V_{SD}	$I_s = 4\text{A}, V_{\text{GS}} = 0\text{V}$	-	-	1.2	V
Continuous Source Current	$T_A=25^\circ\text{C}$	I_s	-	-	13	A

Note1: Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$

Note2: The test condition is $V_{\text{DD}}=24\text{V}, V_{\text{GS}}=10\text{V}, L=0.5\text{mH}, I_{\text{AS}}=13\text{A}$.

Note3: The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.

Note4: The data tested by pulsed, pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.

Note5: This value is guaranteed by design hence it is not included in the production test.

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Typical Characteristics

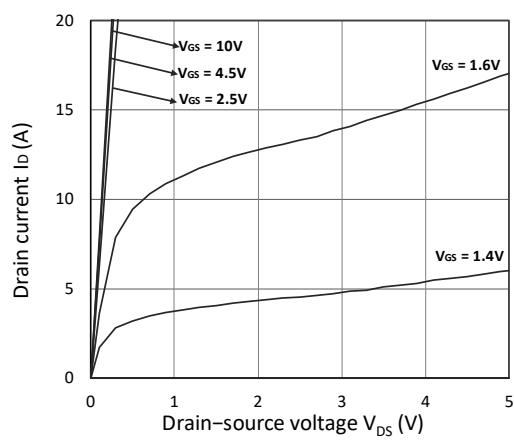


Figure 1. Output Characteristics

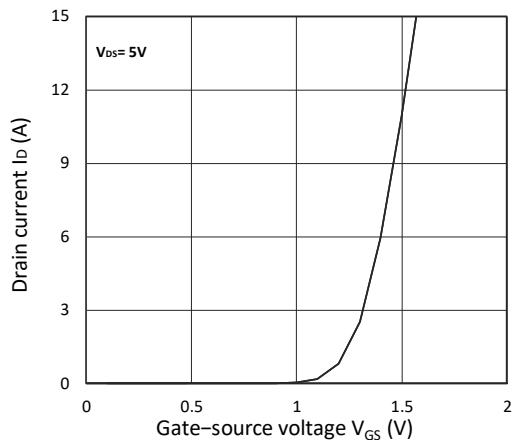


Figure 2. Transfer Characteristics

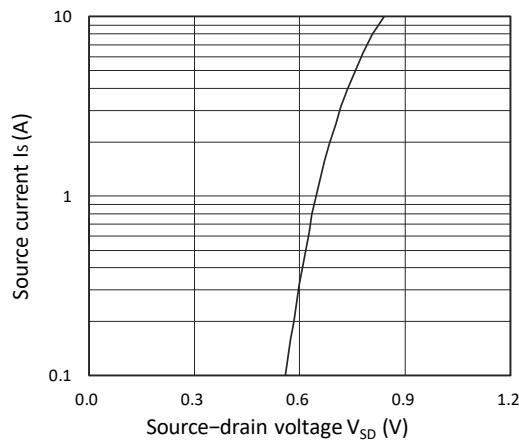


Figure 3. Forward Characteristics of Reverse

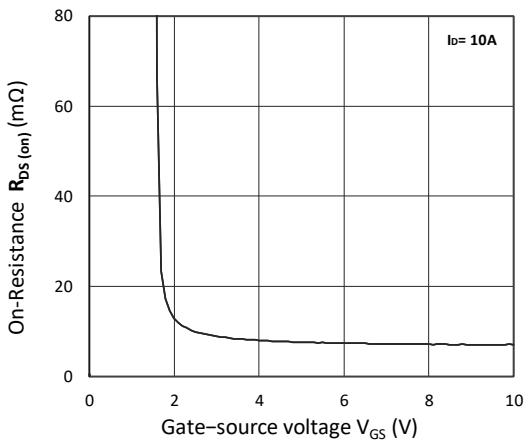


Figure 4. $R_{DS(on)}$ vs. V_{GS}

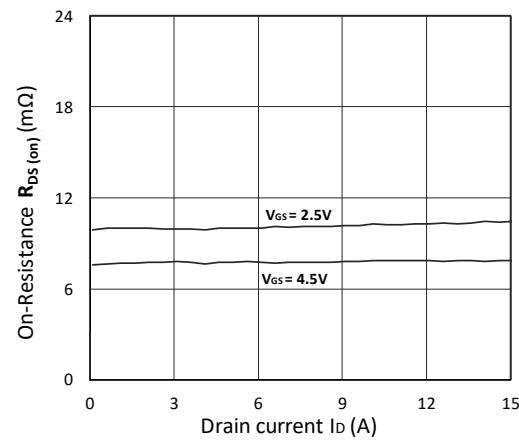


Figure 5. $R_{DS(on)}$ vs. I_D

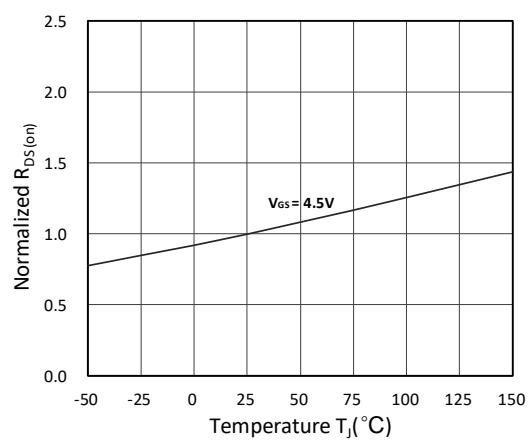
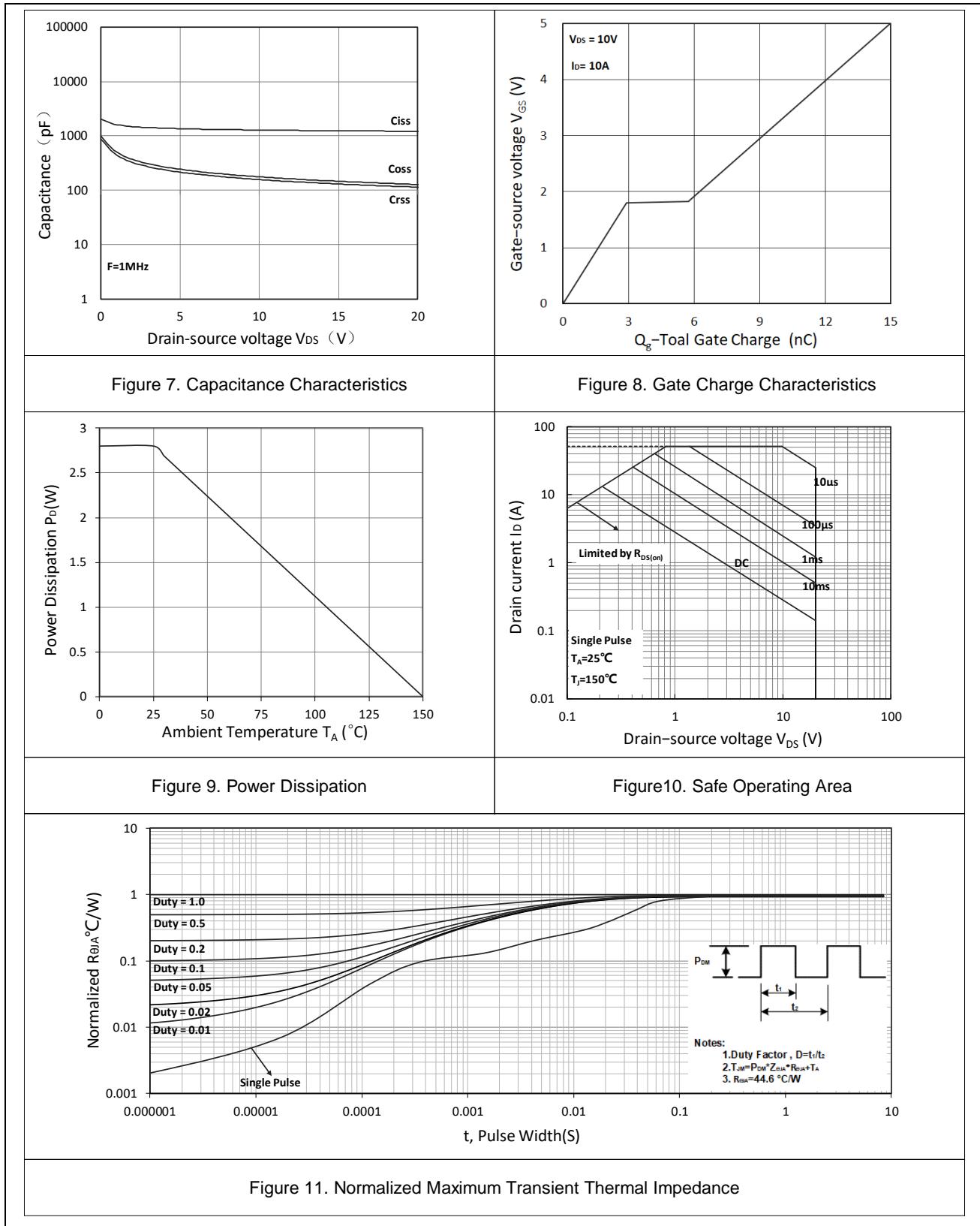


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

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Typical Characteristics(Continued)



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Test Circuit

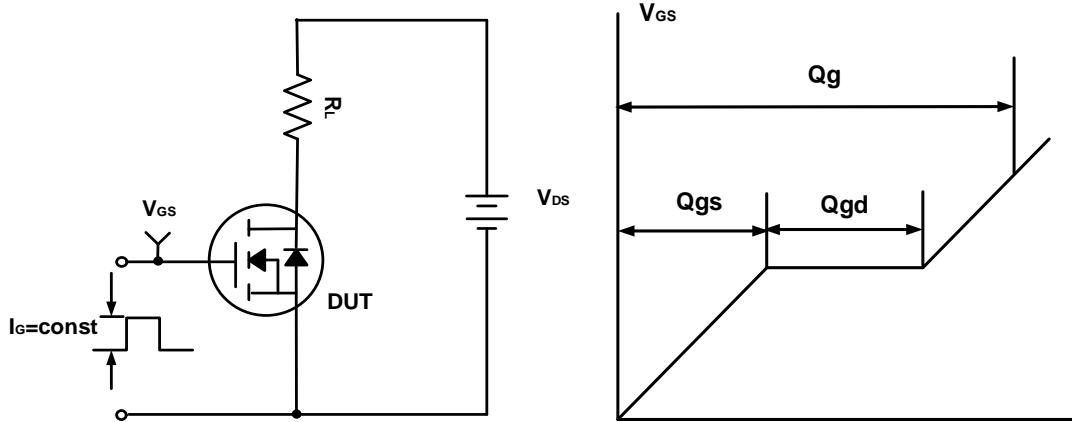


Figure A. Gate Charge Test Circuit & Waveforms

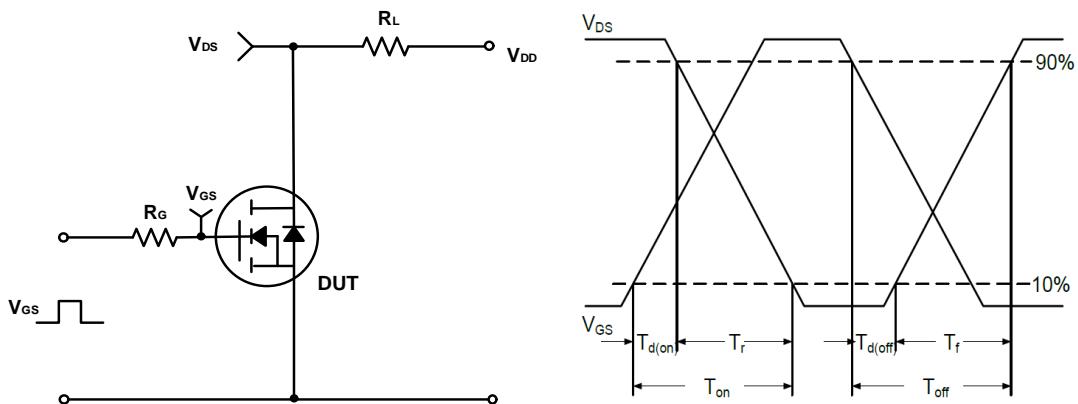


Figure B. Switching Test Circuit & Waveforms

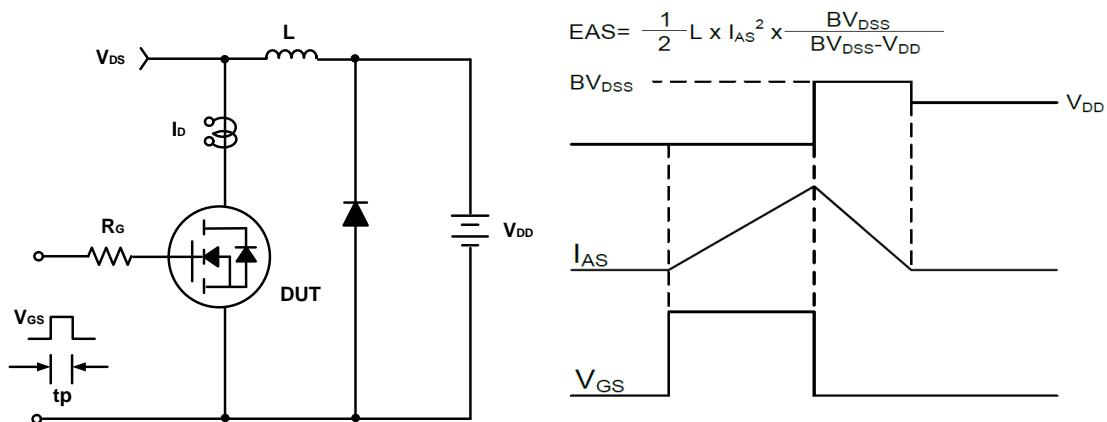


Figure C. Unclamped Inductive Switching Circuit & Waveforms

EMR13N02TS

Package Dimension

DFN2020-6L		
SYMBOL	MILLIMETER	
	MIN	MAX
A	0.50	0.60
A1	0.00	0.05
A3	0.152REF	
b	0.25	0.35
D	1.90	2.10
D1	0.80	1.00
E	1.90	2.10
E1	0.80	1.00
L1	0.46	0.66
e	0.65BSC	
D2	0.25	0.35
L	0.25	0.35

The diagram illustrates the DFN2020-6L package dimensions. It includes a top view showing width D and height E, with PIN 1 marked at the bottom-left corner. A side view shows the thickness A, lead spacing A1, lead length A3, and lead width b. A detailed cross-sectional view shows internal features like D1, D2, L, and E1, along with lead pitch e and lead width b.

Ordering Information

Part	Package	Marking	Packing Information
EMR13N02TS	DFN2020-6L	R13N02S	Tape and Reel

EMR13N02TS

Revision History and Checking Table

Version	Date	Revision Item	Modifier	Function & Spec Checking	Package & Tape Checking
1.0	2022-09-22	Released Version	Pan Shun Ye	Qi Shu Kun	Liu Jia Ying